

ABSTRACT

A method and apparatus for measuring wear of the thickness of a chemical mechanical polishing pad are provided. The apparatus includes a chemical mechanical polishing pad having a plurality of reliefs in a main polishing surface for determining wear of the pad. In one aspect, the pad reliefs comprise through-holes in the pad or extend partially through a thickness of the pad. The method for measuring wear of the thickness of a chemical mechanical polishing pad includes providing a plurality of reliefs in a main polishing surface of the pad and measuring a distance from the main polishing surface to a bottom surface of each of a plurality of the reliefs.

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